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Novel photon detectors



Peter Križan University of Ljubljana and J. Stefan Institute



Introduction: why?

Photon detectors are at the heart of most experiments in particle physics.

Subsystems with photosensors in the Belle II Detector

K_L and muon detector: Resistive Plate Counter (barrel outer layers) Scintillator + WLSF + SiPMs (end-caps , inner 2 barrel layers)

EM Calorimeter: CsI(Tl), waveform sampling

electrons (7GeV)

Beryllium beam pipe 2cm diameter

Vertex Detector 2 layers DEPFET + 4 layers DSSD

> Central Drift Chamber He(50%):C₂H₆(50%), small cells, long lever arm, fast electronics

Particle Identification Time-of-Propagation counter (barrel) Prox. focusing Aerogel RICH (fwd)

positrons (4GeV)

Subsystems with photosensors in LHCb



Components with photosensors in CMS



Photosensors in neutrino experiments: JUNO



... a paramount component

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Photosensors in dark matter experiments

Example: XENON1T

- 1 tonne of liquid Xenon + a gas layer
- Gran Sasso Laboratory LNGS
- S1: scintillations in liquid Xenon (small signal, top and bottom)
- S2: scintillations in the gas phase where electrons get accelerated (large signal, top only)
- Time difference: depth of interaction point



гесенкидан, сјиријана

Introduction: why?

Photon detectors are at the heart of most experiments in particle physics.

Moreover, they are also finding application in other scientific fields (chemistry and biology) and are ubiquitous in society in general.

New environments where we need to detect light (in particular low light levels) \rightarrow need advances in existing technology and transformative, novel ideas to meet the demanding requirements.

Two main lines of R&D are pursued at present:

- Enhance timing resolution.
- Develop photosensors for extreme environments.

Belle II detector: subsystems with R&D for potential photosensor upgrades



Contents

Introduction: why and what kind of photosensor?

- Vacuum-based photodetectors
- Solid state low light level photosensors
- Photodetector R&D at Belle II
- Summary and outlook

Vacuum-based photodetectors







Generic steps:

- Photon → photo-electron conversion in the photocathode
- Photo-electron collection in the multiplication system
- Signal collection



Photomultiplier tube (PMT)



Multiplication on an array of electrodes coated by a secondary emitter material: 1 incoming electron $\rightarrow \sim$ 3-4 emitted electrons



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Multianode photomultiplier tube (MA-PMT)



Pioneered in the HERA-B RICH, later used in the COMPASS, CLASS12 and GlueX RICH detectors

Recent use in the upgraded LHCb RICH detectors; planned for CBM RICH



Excellent performace (excellent single photon detection efficiency, very low noise, low cross-talk), best choice for large areas with no B field

Micro Channel Plate PMT (MCP-PMT)



Multiplication step: a continuous dynode – a micro-channel coated with a secondary emitter material

Micro Channel Plate PMT (MCP-PMT)



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Micro Channel Plate PMT: properties

Very fast: single photon detection with sigma of ~30-40 ps



MCP PMTs work well in magnetic fields → performance depends on the diameter of the microchannels



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MCP-PMT: single photon pulse height and timing



Photoelectron back-scattering produces a rather long tail in timing distribution and position resolution.

Photoelectron backscattering reduces collection efficiency and gain, and contributes to cross-talk in multi-anode PMTs



S.Korpar@PD07

Modelling MCP-PMT: Photoelectrons in a uniform electric field

Photoelectrons travel from the photocathode to the electron multiplier (uniform electric field $\frac{U}{l}$, initial energy $E_0 \ll Ue_0$):

photoelectron range

$$d_0 \approx 2l \sqrt{\frac{E_0}{Ue_0}} sin(\alpha)$$

and maximal travel time (sideway start)

$$t_0 \approx l \sqrt{\frac{2m}{Ue}}$$

• time difference between downward and sideways initial direction

$$\Delta t \approx t_0 \sqrt{\frac{E_0}{Ue_0}}$$



Time resolution vs PC-MCP1 voltage



maximum delay is twice the photoelectron travel time

• time of arrival of elestically scattered photoelectrons: flat distribution up to max $t_1 = 2t_0$

Example (U = 200 V, $E_0 = 1 \text{ eV}$, l = 6 mm) photoelectron:

- max range $d_0 \approx 0.8$ mm
- p.e. transit time $t_0 \approx 1.4$ ns
- $\Delta t \approx 100 \text{ ps}$

backscattering:

- max range $d_1 = 2l = 12 \text{ mm}$
- max delay $t_1 = 2.8$ ns

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Modelling MCP-PMT: time resolution vs photocathode-to-microchannel-plate voltage difference

Time difference between downward and sideways initial direction (previous slide)

$$\Delta t \approx t_0 \sqrt{\frac{E_0}{Ue_0}}$$

This difference is proportional to the time resolution – sigma of the main peak in the time response of the MCP-PMT



Time resolution vs PC-MCP1 voltage U

LAPPD (large area picosecond photodetector) Gen II

Characteristics (Incom):

- size 230 mm x 220 mm x 22 mm (243 mm x 274 mm x 25.2 mm with mounting case)
- borosilicate back plate with interior resistive ground plane anode – 5 mm thick
- capacitively coupled readout electrode
- MCPs with 20 μ m pores at 20 μ m pitch
- two parallel spacers (active fraction \approx 97 %)
- gain $\approx 5 \cdot 10^6$ @ ROP (825 V/MCP, 100 V on photocathode)
- peak QE $\approx 25\%$
- Dark Count rate @ ROP: ~ 70 kHz/cm2 with 8x10⁵ gain







MCP PMT ageing

MCP PMTs: photo-cathode degradation due to ion feedback, main concern in high intensity experiments.

Ions are liberated from the microchannel walls during the multiplication process.

 \rightarrow Long-standing problem for this sensor type.

ALD (atomic layer deposition) coating of MCP microchannels \rightarrow ${\sim}100x$ photo-cathode lifetime increase

- Hamamatsu 1-inch YH0205 (>20 C/cm²) [K. Inami, 2021]
- No QE degradation for Photonis MCP-PMT (R2D2) to >34 C/cm²
- Little QE degradation in LAPPD 8-inch up to 5.6 C/cm² [V. A. Chirayath, CPAD2021]





Possible Future of Electron Multiplication

H. van der Graaf et al., NIM A847 (2017) 148 Tynodes (\rightarrow Time Photon Counter) Transmission Reflection Transmission mode dynode \rightarrow tynode Fabrication of tynodes (MgO ALD, diamond) Θ using MEMS technology Photon Support "Anode" is a CMOS chip (e.g., TimePix) Substrate Very promising properties Diamond dvnode Tynod Very compact; high B-field tolerance; very fast Very low DCR; very good 2D spatial resolution Detecting chip Amplified signal

MCP-PMT with CMOS anode

Conceptual design for 4D detection of single photons

Hybrid concept: MCP-PMT where the pixelated anode is an ASIC (CMOS) embedded inside the vacuum Prototype with Timepix4 ASIC as anode (array of 23k pixels)

Envisaged performance

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 $<\!100$ ps time resolution and 5-10 μm spatial resolution Rate capability of $>\!100$ MHz/cm² ($<\!2.5$ Ghits/s @ 7 cm² area)

Low gain (~104) operation possible \rightarrow x100 lifetime increase





Hybrid photodetectors (HPD, HAPD)



Photo-electron acceleration in a static electric field (8kV to 25 kV)

Photo-electron detection with

- Segmented PIN diode (HPD)
- Avalanche photo diode (HAPD)
- Silicon photomultiplier (VSiPMT)

Employed on a large scale:

- HPD: RICH1+RICH2 of LHCb (Run 1+2), CMS HCAL
- HAPD: Aerogel RICH detector of Belle II



HAPD: photoelectron backscattering in magnetic field



In the HAPD of the Belle II ARICH, around 20% of photoelectrons backscatter and the maximum range is twice the distance from photocathode to APD ~40mm (similar to MCP-PMT).

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In magnetic field (perp. to the HAPD window) scattered photoelectrons follow magnetic field lines and fall back to the same pad

Photoelectron energy is deposited at the same pad









Solid state low light level photosensors: Silicon photomultipliers SiPM

An array of APDs operated in Geiger mode – above APD breakdown voltage (microcells or SPADs – single photon avalanche diodes) Detection of photons:

- absorbed photon generates an electron-hole pair
- an avalanche is triggered by the carrier in the high field region \rightarrow signal
- voltage drops below breakdown and avalanche is quenched (passive or active quenching)
- each triggered microcell contributes the same amount of charge to the signal



SiPM: noise

- Dark counts are produced by thermal generation of carriers, trap assisted tunnelling or band gap tunnelling
- Signal from dark counts is equal to the single photon response
- Typical rates went from $\approx 1 MHz/mm^2$ to below $100 kHz/mm^2$ for more recent devices
- Roughly halved for every -8°C
- Increases linearly with fluence
- Optical cross-talk produced when photons emitted in avalanche initiate signal in neighbouring cell, reduced by screening – trenches
- After-pulses produced by trap-release of carriers or delayed arrival of optically induced carrier in the same cell









SiPM: parameter correlation

Higher overvoltage:

➢ higher field:

- higher avalanche trigger probability \rightarrow higher PDE
- faster signal \rightarrow better timing
- ≻ higher gain:
 - better signal to noise (electronic)
 - more optical cross-talk \rightarrow higher ENF, worse timing
 - more after-pulses





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VUV SiPM for cryogenic applications

LAr, LXe applications:

- > VUV sensitivity required:
 - 128 nm (LAr), 178 nm (LXe) •
 - CR (Hz/mm²) optimization of anti-reflective coating ARC •
 - PDE $\approx 20\%$
- > cryogenic temperatures:
 - low DCR $\approx 10 \text{mHz/mm}^2$ dominated by band-band tunnelling, reduced by low-field avalanche region
 - higher after-pulse rate $\approx 10\%$ •



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10 5

10 4

10 ³

10²

10¹

10⁰ 10-1 10-2

10-3

0

Cell size = 25 µm

SF - 4 V

SF - 6 V

🗕 LF - 6 V

50

100

150

Temperature (K)

200

250

300



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SiPM: single photon timing

Intrinsic TTS of SiPM microcells is extremely fast, < 20 ps for single microcells (SPAD), but timing deteriorates for larger devices. The main contributions:

- nonuniformity within microcell (edges)
- spread between microcells
- overall SiPM capacitance
- λ dependence tails

Comparison of timing properties for single $50\mu m$ SPAD, $1 \times 1 mm^2$ and $3 \times 3 mm^2$ SiPMs with the same SPAD for microcells:

- timing improves with higher overvoltage larger pulses, at the expense of increased SiPM noise
- best timing resolutions for single cell signals are $\sigma \approx 21 \text{ ps}, 32 \text{ ps}$ and 77 ps
- TTS deterioration mainly due to a larger overall capacitance \rightarrow reduced signal slope, $\sigma_t \approx \sigma_{el.} \left(\frac{dU}{dt}\right)^{-1}$







SiPM: timing variation

Variation of TTS over the device surface can contribute to overall time spread:

- variation within micro-cell
- variation for different microcells





FBK: Masking of outer regions of micro-cells: Improve signal peaking and mask areas of micro-cell with worse timing

SiPM: timing for multi-cell signals

Optical cross-talk contribution to multi-cell signals spoils timing distribution – does not scale with $\frac{1}{N^{1/2}}$:

- two components for 2-micro-cell signals:
 - double photon events proper scaling
 - single photon with cross-talk, timing somewhere between single and double micro-cell signals and resolution is worse
- ratio between contributions changes with light intensity confirming optical cross-talk origin

• even more components for multi-micro-cell signals



SiPM: timing test with pico-second laser

- AdvanSiD SiPM ASD-NUV3S-P-40 •
- OV=6V, T=-25°C

24000

22000

20000

10000

8000 6000 4000

6000

2000 1000

• blue laser λ =408nm, ~ 35ps FWHM



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Reduction of optical crosstalk

Starting from the NUV-HD technology, FBK and Broadcom jointly developed the NUV-HD-MT technology, adding metal-filled deep trench isolation to strongly suppress optical crosstalk.

Other changes: low electric field variant, layout optimized for timing.



Conceptual drawing of the NUV-HD-MT, with the addition of metal-filled Deep Trench Isolation.



Reduction of optical crosstalk probability in NUV-HD-MT, compared to the "standard" NUV-HD. Measurement without encapsulation resin, i.e. only considering internal crosstalk probability.

A. Gola, RICH2022

Light concentrators

At the device level (lenses, Winston cones):

reduce active are – reduce DCR (tolerate higher fluences)

use smaller faster devices

At the micro-cell level (micro-lenses, diffractive lenses, meta lenses):

• compensate for low fill factor – small cells, dSiPM

• concentrate light in cell centre – better timing

Higher concentration – narrower angular acceptance

Imaging light concentrators:

smaller photon impact angles on the sensor

can be used with position sensitive arrays

Non-imaging light concentrators:

 larger photon impact angles on the sensor – directly coupled to sensor



SiPM RICH with light concentrators

RICH photon detector module prototype:

- Hamamatsu 64 channel MPPC module S11834-3388DF, 8×8 array of 3×3 mm² SiPMs @ 5 mm pitch
- matching array of quartz light concentrators used
- two 20 mm thick aerogel tiles in focusing configuration (n = 1.045, 1.055)
- tested in 5 GeV electron beam at DESY







E. Tahirović et al., NIM A787 (2015) 203

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Microlenses

Micro-lens array coupled to SPAD array

- CMOS SPAD array, 128x128 $6\mu m$ diameter @25 μm pitch 5% fill factor
- matching polymer plano-convex micro-lens array





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SiPMs: Radiation damage



Show stopper at fluences above ~10¹¹ in case single (or few) photon sensitivity is required!

(e.g. expected fluence in the ARICH area of Belle II: 2-20 $10^{11}\,n\,\,cm^{-2}$)

- \rightarrow Use of wave-form sampling readout electronics
- \rightarrow Operating the SiPMs at lower temperature
- \rightarrow Annealing periodically (annealing at elevated temperature is preferred)
- \rightarrow Reducing recovery time to lower cell occupancy
- \rightarrow Radiation resistant SiPMs, other materials?

SiPMs: Radiation damage

Beyond $10^7 \div 10^8 n_{eq}$ /cm² little correlation between the DCR before and after irradiation:

- All technologies seem to "converge" towards similar values
- Independence of bulk damage from contaminants in the SiPM starting material?



DCR (dark count rate) vs fluence



Room temperature annealing (20-25°C) for samples irradiated to 6.4·10¹¹ 1 MeV n_{eq}/cm² Little effect, knee point at around 1.5·10³ min (~1 day)

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A. Gola, RICH2022

SiPMs: Radiation damage, annealing at elevated temperatures

Dark counts at -30C of a Hamamatsu S13360-1350CS SiPMs: non irradiated (blue) and irradiated up to 10^{11} (yellow), 10^{12} (green) and 10^{13} (orange) n_{eq}/cm²





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SiPMs: annealing after irradiation



The temperatures at which single photon can be resolved at an overvoltage of 9 V vs. different irradiation levels. The error bars indicate the 40°C steps in which the measurements were carried out.



DCR measurements for each of the SiPMs at liquid nitrogen temperature before and after the annealing (dashed)

Studies for Belle II ARICH upgrade

Dania Consuegra Rodríguez et al, Eur. Phys. J. C (2024) 84:970

Belle II detector: subsystems with R&D for potential photosensor upgrades





Possible Upgrade of ARICH



 double layer focusing aerogel radiator (20+20 mm)
 160 mm expansion gap
 photon detector : 420 HAPDs -Hybrid Avalanche Photo Detectors



ARICH K efficiency vs. π misidentification probability



Belle II ~2033

In case of a further increase of the luminosity beyond the design value

 Higher backgrounds
 HAPD – accumulated dose too high will not be able to operate
 Search for new technologies: Candidates: SiPM, MCP-PMT

LAPPDs?

Possible LAPPD tiling scheme





LAPPD evaluation

- Two 10 um devices acquired
- LAPPD installed in the dark box:
- CAEN HiVolta (DT1415ET), 8 Ch Reversible 1 kV/1 mA Desktop HV Power Supply – floating channels
 - 1 kV/1 mA and 0.6 W(!) per channel
- Measure response in the lab with modular electronics, FastIC and PETSys
- Standard setup with QDC, TDC, 3D stage ...
 - TDC value corrected for time-walk
- ALPHALAS PICOPOWER[™]-LD Series of Picosecond Diode Lasers –405 nm
 - FWHM ≈20ps
 - light spot diameter on the order of 100μ m
- Custom segmentation to study the capacitive coupling and the charge spread





ch.5

ch.4 ch.3 ch.1 + ch.2

ch.0



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LAPPD #162 timing and signal charge

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- oscilloscope screenshot with laser spot at the center of D2 pad
- TDC(yellow) and pulse integral(blue) histograms
- TDC main peak FWHM is 67 ps corresponding to sigma below 30 ps.^B
- Average pulse integral is 25 pVs -> ~ 3e6 electrons







VSet	VMon	IMon	lSet
200.00	200.18	0.3500	5.00
825.00	825.62	176.7500	200.00
200.00	200.22	0.0690	5.00
825.00	825.52	154.2340	200.00
200.00	199.98	0.0930	5.00

R.Pestotnik, ARICH meeting@ 47th B2GM Jan 26 2024

LAPPD – charge sharing in Gen II capacitively coupled electrode readout



- fraction of the signal on channel 3 vs laser spot x position: $f(x) = \frac{q_3}{\sum_i q_i}$
- scan between the centres of pads 2 and 3 (top)



- central slice where signal is equally split between the pads (bottom)
- narrow peak is due to the light spot size and photoelectron spread
- longer tail from photoelectron backscattering $\approx 6 \text{ mm on each side} \rightarrow \approx 3 \text{ mm PC} \text{MCP1}$ distance





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#162 (2mm ceramic) vs. #109 (5mm borosilicate window)

- An example plot for charge sharing between pads D3-D5 for:
 - 162 (top) compared with similar plot for
 - 109 (bottom).
- One can see reduced signal spread as expected.
- From backscatter component range (~2mm) one can also see that PC-MCP1 in distance was reduced:
 - from about 3mm (109)
 - to about 1mm (162).



R.Pestotnik, ARICH meeting@ 47th B2GM Jan 26 2024



LAPPD – timing distribution



LAPPD – timing vs PC-MCP1 voltage



Time-walk corrected TDCs for different PC-MCP1 voltages



Time resolution vs PC-MCP1 voltage

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KLM upgrade, option 1



Regular scintillator strips, original design (a1) Scintillator with a reflective layer WLS fiber SiPM D(cm) H TH(p.e.) (c1) Number of p.e. (d1) Preamplifier 1.5 m scintillation detector Distance to SIPM (cm) Performance in cosmic ray testing Single channel: (e1) H.Y. Zhang et al., $\epsilon > 95\%$ arXiv:2312.02552 Accepted by JINST $\sigma_T < 1.5 ns$



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The total number of responsed strip

The total number of responsed strips



KLM upgrade, option 2



Precise time measurement –

for example for the time-of-flight measurement of K_L velocity/momentum



Thicker scintillators with longer attenuation lengths and large areas of SiPM can improve photon collection – and time-of-arrival resolution.



Time resolution of a long scintillator bar (GNKD_new, 2cm)



Summary and outlook

Next generation of experiments in particle physics: faster timing, wider spectral range and improved radiation tolerance.

Many new interesting developments are underway, in particular in SiPMs and MCP-PMTs – not all of them could be covered in this talk.

A detector R&D collaboration (DRD4) has been set-up to facilitate collaboration in this area of research, started in January 2024. Worth considering to join one of the activities.

At Belle II, we are investigating possible upgrade scenarios, and carrying out very interesting photosensor R&D.



More to read

The write-up of a talk at PSD13 (Oxford, 2023) that covers most of the topic discussed here (P.K., NIMA 1065 (2024) 169482) is available (open access) at https://doi.org/10.1016/j.nima.2024.169482

Web pages of our detector lab <u>https://photodetectors.ijs.si</u> and analysis activities <u>https://faime.ijs.si/</u>

DRD4 Collaboration https://drd4.web.cern.ch/

MCP PMT readout: capacitive coupling vs. internal anodes

Secondary electrons spread out when traveling from the MCP-out electrode to the anode and can hit more than one anode \rightarrow Charge sharing Can be used to improve spatial resolution.





BURLE/Photonis PLANACON (internal anodes)



Fraction of the charge detected by the right pad as a function of red laser spot position

Capacitive coupling vs. internal anodes: signal spread comparison for two MCP PMTs with the same pad size, same range: charge sharing is more effective for capacitive coupling (spreads over larger area) - advantage or not: depends on the usage